

WHAT IS CLAIMED IS:

1. A heat dissipation module for CPU, suitable to be installed on a retention frame disposed around the CPU, the heat dissipation module comprising:

a heat dissipation device having a plurality of fins, the fins defining flow
5 passageways therebetween;

a fan-fixing frame located on the heat dissipation device, the fan-fixing frame having a top plate, four posts, and a plurality of elastic pressing components, the posts extending downwardly from four corners of the top plate, the posts each having a clipping element at a bottom thereof, the elastic
10 pressing components being installed on the top plate; and

a fan fixed on the top plate of the fan-fixing frame;

wherein the fan-fixing frame is disposed on the retention frame, the clipping elements at the bottoms of the posts of the fan-fixing frame respectively clipping clipping holes at four supporting protrusions of the retention frame,
15 the elastic pressing components thereby elastically pressing the heat dissipation device to abut against a heat-exhausting surface of the CPU.

2. The heat dissipation module as claimed in claim 1, wherein the heat dissipation device defines a through hole penetrating from a top surface to a bottom surface of the heat dissipation device, the flow passageways penetrating
20 through the top surface, the bottom surface and outer surfaces of the heat dissipation device, the heat dissipation device defining a wind guiding surface on an inner wall of the through hole near the top surface and a plurality of wind guiding holes in the inner wall near the bottom surface, and the wind guiding holes communicating with the flowing passageways.

3. The heat dissipation module as claimed in claim 2, further comprising a thermal conductive plate, the thermal conductive plate being fixed at the
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bottom surface of the heat dissipation device corresponding to the through hole for being disposed on the heat-exhausting surface of the CPU.

4. The heat dissipation module as claimed in claim 1, wherein the top plate of the fan-fixing frame defines an opening hole and four connection holes, the fan facing to the opening hole and four screws penetrating through four corners of the fan and screwing to the related four connection holes.

5. The heat dissipation module as claimed in claim 1, wherein the four posts of the fan-fixing frame each have a hollow projection disposed above the clipping element.

6. The heat dissipation module as claimed in claim 1, wherein the fan-fixing frame has two baffles respectively extending downwardly from two opposite sides of the top plate and two side clips respectively extending downwardly from another two opposite sides of the top plate, the baffles and the side clips abutting against four outer edges of the heat dissipation device.

7. The heat dissipation module as claimed in claim 1, wherein the elastic pressing components of the fan-fixing frame each include a connection part and a spring, the connection part having a hooking portion at a top end thereof and a pressing portion at a bottom end thereof, the spring being located around the connection part, the hooking portion being inserted onto a related piercing hole defined at the top plate of the fan-fixing frame, and the spring being disposed between the top plate and the pressing portion.